

Fair-Rite P/N **296166681**

61 Material Grade

Nominal Chemical Composition

<u>Compound</u>	<u>CAS Number</u>	<u>wt %</u>	Wt of core (g)=	
			1.200	
Fe2O3	1309-37-1	72	0.864	Compound Weight (g) Breakdown of 61 Material
ZnO	1314-13-2	13	0.156	
NiO	1313-99-1	11	0.132	
MnO	1344-43-0	2	0.024	
CuO	1317-38-0	1	0.012	
CoO	1307-96-6	1	0.012	

Pb- Free Plated Round Cu Wire

<u>Element</u>	<u>CAS Number</u>	<u>wt%</u>	Wt of wire (g)=	
			0.200	
Cu	7440-50-8	92.9	0.1858	Element Weight (g) Breakdown of Pb- Free Plated Round Cu Wire
Plating:				
Ni	7440-02-0	1.2	0.0024	
Sn	7440-31-5	5.9	0.0118	

Calculated Maximum Levels of RoHS Restricted Substances Present in 61 Material Grade

<u>Impurity Substance</u>	<u>RoHS Threshold (ppm)</u>	<u>ppm</u>	Wt of core (g)=	
			1.200	
Hexavalent chromium (Cr+6)	1000	0.00	0	RoHS Impurity Substance Weight (g) Breakdown of 61 Material
Cadmium (Cd)	100	3.70	0.00000444	
Mercury (Hg)	1000	0.10	0.00000012	
Lead (Pb)	1000	7.00	0.00000084	
Polybrominated biphenyl (PBB)	1000	0.00	0	
Polybrominated diphenyl (PBDE)	1000	0.00	0	
Bis(2-Ethylhexyl) phthalate (DEHP)	1000	0.00	0	
Benzyl butyl phthalate (BBP)	1000	0.00	0	
Dibutyl phthalate (DBP)	1000	0.00	0	
Diisobutyl phthalate (DIBP)	1000	0.00	0	

Supporting notes:

1. P/N 296166681 consists of:
 - a core 61 Material Grade
 - b wire Pb- Free Plated Round Cu Wire
2. Moisture Sensitivity Level (MSL)= 1
3. Max Reflow Temp= 260 degC
4. Max Time at Max Reflow Temp= 10 sec
5. RoHS 6/6 Compliant Terminations/ Wire are backwards compatible with standard Soldering Processes
6. RoHS Conversion Date= 1/1/2005
RoHS Compliance Marking is
7. Contained on Shipping Labels